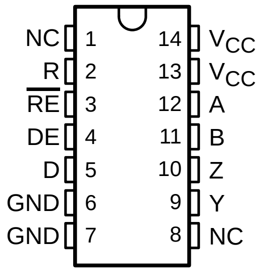
- **Meet or Exceed the Requirements of TIA/EIA-422-B, TIA/EIA-485-A† and ITU Recommendation V.11**
- **High-Speed Advanced Low-Power Schottky Circuitry**
- **Designed for 25-Mbaud Operation in Both Serial and Parallel Applications**
- **Low Skew Between Devices . . . 6 ns Max**
- **Low Supply-Current Requirements . . . 30 mA Max**
- **Individual Driver and Receiver I/O Pins With Dual V_{CC} and Dual GND**
- **Wide Positive and Negative Input/Output Bus Voltage Ranges**
- **Driver Output Capacity . . . ±60 mA**
- **Thermal Shutdown Protection**
- **Driver Positive- and Negative-Current Limiting**
- **Receiver Input Impedance . . . 12 kΩ Min**
- **Receiver Input Sensitivity . . . ±200 mV Max**
- **Receiver Input Hysteresis . . . 60 mV Typ**
- **Operate From a Single 5-V Supply**
- **Glitch-Free Power-Up and Power-Down Protection**

SN65ALS180 . . . D PACKAGE
SN75ALS180 . . . D OR N PACKAGE
(TOP VIEW)



NC – No internal connection

description/ordering information

The SN65ALS180 and SN75ALS180 differential driver and receiver pairs are integrated circuits designed for bidirectional data communication on multipoint bus-transmission lines. They are designed for balanced transmission lines and meet TIA/EIA-422-B, TIA/EIA-485-A, and ITU Recommendation V.11.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	PDIP (N)	Tube of 25	SN75ALS180N	SN75ALS180N
	SOIC (D)	Tube of 50	SN75ALS180D	75ALS180
		Reel of 2500	SN75ALS180DR	
–40°C to 85°C	SOIC (D)	Tube of 50	SN65ALS180D	65ALS180
		Reel of 2500	SN65ALS180DR	

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

† These devices meet or exceed the requirements of TIA/EIA-485-A, except for the Generator Contention Test (para. 3.4.2) and the Generator Current Limit (para. 3.4.3). The applied test voltage ranges are –6 V to 8 V for the SN75ALS180 and –4 V to 8 V for the SN65ALS180.

description/ordering information (continued)

The SN65ALS180 and SN75ALS180 combine a 3-state differential line driver and a differential input line receiver, both of which operate from a single 5-V power supply. The driver and receiver have active-high and active-low enables, respectively, that can be connected together externally to function as a direction control. The driver differential outputs and the receiver differential inputs are connected to separate terminals for greater flexibility and are designed to offer minimum loading to the bus when the driver is disabled or V_{CC} = 0.

These ports feature wide positive and negative common-mode voltage ranges, making the device suitable for party-line applications.

Function Tables

DRIVER

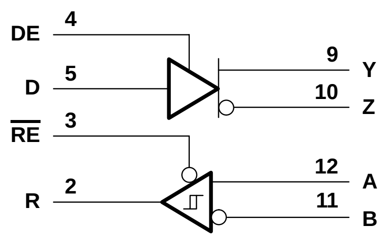
INPUT D	ENABLE DE	OUTPUTS Y	Z
H	H	H	L
L	H	L	H
X	L	Z	Z

RECEIVER

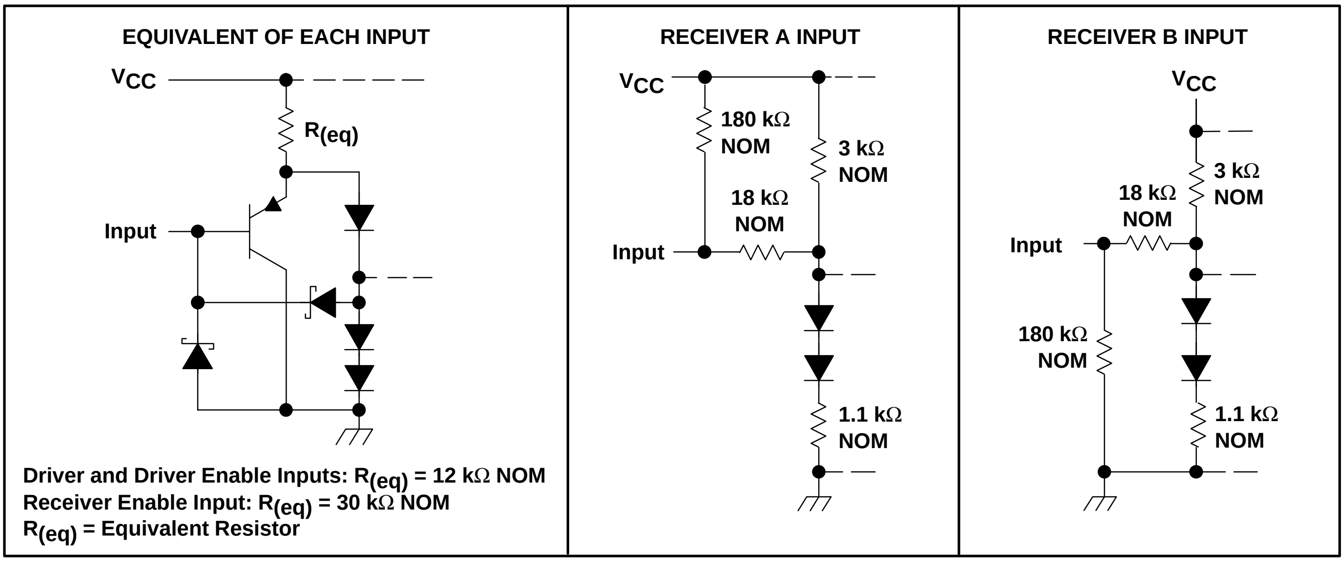
DIFFERENTIAL INPUTS A–B	ENABLE $\overline{RE}$	OUTPUT R
V_{ID} ≥ 0.2 V	L	H
–0.2 V < V_{ID} < 0.2 V	L	?
V_{ID} ≤ –0.2 V	L	L
X	H	Z
Open	L	H

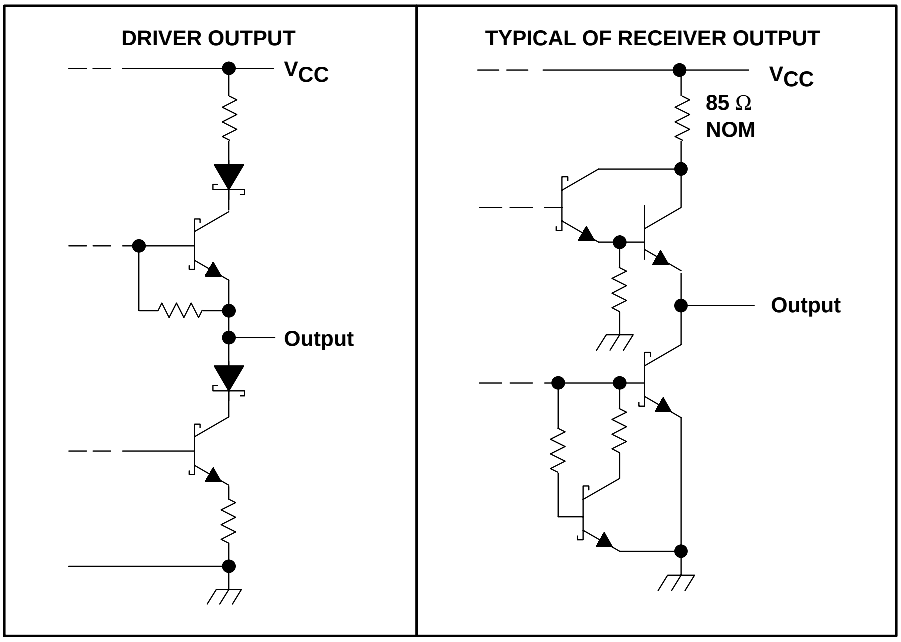
H = high level, L = low level, ? = indeterminate,
X = irrelevant, Z = high impedance (off)

logic diagram (positive logic)



schematics of inputs and outputs





absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC} (see Note 1) . . . . . 7 V
Voltage range at any bus terminal . . . . . –10 V to 15 V
Enable input voltage, V_I . . . . . 5.5 V
Package thermal impedance, θ_{JA} (see Notes 2 and 3): D package . . . . . 86°C/W
N package . . . . . 80°C/W
Operating virtual junction temperature, T_J . . . . . 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds . . . . . 260°C
Storage temperature range, T_{st} . . . . . –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values, except differential I/O bus voltage, are with respect to network ground terminal.
2. Maximum power dissipation is a function of T_J(max), θ_{JA}, and T_A. The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) – T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions

			MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage		4.75	5	5.25	V
V_I or V_{IC}	Voltage at any bus terminal (separately or common mode)				12	V
					–7	
V_{IH}	High-level input voltage	D, DE, and $\overline{RE}$	2			V
V_{IL}	Low-level input voltage	D, DE, and $\overline{RE}$			0.8	V
V_{ID}	Differential input voltage (see Note 4)				±12	V
I_{OH}	High-level output current	Driver			–60	mA
		Receiver			–400	µA
I_{OL}	Low-level output current	Driver			60	mA
		Receiver			8	
T_A	Operating free-air temperature	SN65ALS180	–40		85	°C
		SN75ALS180	0		70	

NOTE 4: Differential-input/output bus voltage is measured at the noninverting terminal, A/Y, with respect to the inverting terminal, B/Z.

DRIVERS

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS†		MIN	TYP‡	MAX	UNIT
V_{IK}	Input clamp voltage	I_I = –18 mA				–1.5	V
V_O	Output voltage	I_O = 0		0		6	V
$\|V_{OD1}\|$	Differential output voltage	I_O = 0		1.5		6	V
$\|V_{OD2}\|$	Differential output voltage	R_L = 100 Ω,	See Figure 1	1/2 V_{OD1} or 2§			V
		R_L = 54 Ω,	See Figure 1	1.5	2.5	5	
V_{OD3}	Differential output voltage	V_{test} = –7 V to 12 V,	See Figure 2	1.5		5	V
$\Delta\|V_{OD}\|$	Change in magnitude of differential output voltage¶	R_L = 54 Ω or 100 Ω,	See Figure 1			±0.2	V
V_{OC}	Common-mode output voltage	R_L = 54 Ω or 100 Ω,	See Figure 1			3 –1	V
$\Delta\|V_{OC}\|$	Change in magnitude of common-mode output voltage¶	R_L = 54 Ω or 100 Ω,	See Figure 1			±0.2	V
I_O	Output current	Output disabled (see Note 5)	V_O = 12 V			1	mA
			V_O = –7 V			–0.8	
I_{IH}	High-level input current	V_I = 2.4 V				20	μA
I_{IL}	Low-level input current	V_I = 0.4 V				–400	μA
I_{OS}	Short-circuit output current#	V_O = –6 V	SN75ALS180			–250	mA
		V_O = –4 V	SN65ALS180			–250	
		V_O = 0	All			–150	
		V_O = V_{CC}	All			250	
		V_O = 8 V	All			250	
I_{CC}	Supply current	No load	Driver outputs enabled, Receiver disabled		25	30	mA
			Outputs disabled		19	26	

† The power-off measurement in TIA/EIA-422-B applies to disabled outputs only and is not applied to combined inputs and outputs.
‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.
§ The minimum V_{OD2} with 100-Ω load is either 1/2 V_{OD2} or 2 V, whichever is greater.
¶ $\Delta|V_{OD}|$ and $\Delta|V_{OC}|$ are the changes in magnitude of V_{OD} and V_{OC}, respectively, that occur when the input is changed from a high level to a low level.
# Duration of the short circuit should not exceed one second for this test.
NOTE 5: This applies for both power on and off; refer to TIA/EIA-485-A for exact conditions. The TIA/EIA-422-B limit does not apply for a combined driver and receiver terminal.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature

PARAMETER		TEST CONDITIONS			MIN	TYP‡	MAX	UNIT
$t_{d(OD)}$	Differential output delay time	R_L = 54 Ω,	C_L = 50 pF,	See Figure 3	3	8	13	ns
	Pulse skew ($\|t_{d(ODH)} - t_{d(ODL)}\|$)	R_L = 54 Ω,	C_L = 50 pF,	See Figure 3		1	6	ns
$t_{t(OD)}$	Differential output transition time	R_L = 54 Ω,	C_L = 50 pF,	See Figure 3	3	8	13	ns
t_{PZH}	Output enable time to high level	R_L = 110 Ω,	See Figure 4			23	50	ns
t_{PZL}	Output enable time to low level	R_L = 110 Ω,	See Figure 5			19	24	ns
t_{PHZ}	Output disable time from high level	R_L = 110 Ω,	See Figure 4			8	13	ns
t_{PLZ}	Output disable time from low level	R_L = 110 Ω,	See Figure 5			8	13	ns

‡ All typical values are at V_{CC} = 5 V and T_A = 25°C.

SYMBOL EQUIVALENTS

DATA-SHEET PARAMETER	TIA/EIA-422-B	TIA/EIA-485-A
V_O	V_{oa}, V_{ob}	V_{oa}, V_{ob}
$\|V_{OD1}\|$	V_o	V_o
$\|V_{OD2}\|$	V_t (R_L = 100 Ω)	V_t (R_L = 54 Ω)
$\|V_{OD3}\|$		V_t (test termination measurement 2)
V_{test}		V_{tst}
$\Delta\|V_{OD}\|$	$\|\|V_t\| - \|\overline{V}_t\|\|$	$\|\|V_t\| - \|\overline{V}_t\|\|$
V_{OC}	$\|V_{os}\|$	$\|V_{os}\|$
$\Delta\|V_{OC}\|$	$\|V_{os} - \overline{V}_{os}\|$	$\|V_{os} - \overline{V}_{os}\|$
I_{OS}	$\|I_{sa}\|$, $\|I_{sb}\|$	
I_O	$\|I_{xa}\|$, $\|I_{xb}\|$	I_{ia}, I_{ib}

RECEIVERS

electrical characteristics over recommended ranges of common-mode input voltage, supply voltage, and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MIN	TYP†	MAX	UNIT
V_{IT+}	Positive-going input threshold voltage	V_O = 2.7 V,	I_O = –0.4 mA				0.2	V
V_{IT-}	Negative-going input threshold voltage	V_O = 0.5 V,	I_O = 8 mA		–0.2‡			V
V_{hys}	Hysteresis voltage ($V_{IT+} - V_{IT-}$)					60		mV
V_{IK}	Enable-input clamp voltage	I_I = –18 mA					–1.5	V
V_{OH}	High-level output voltage	V_{ID} = 200 mV,	I_{OH} = –400 µA,	See Figure 6	2.7			V
V_{OL}	Low-level output voltage	V_{ID} = –200 mV,	I_{OL} = 8 mA,	See Figure 6			0.45	V
I_{OZ}	High-impedance-state output current	V_O = 0.4 V to 2.4 V					±20	µA
I_I	Line input current	Other input = 0 V (see Note 6)	V_I = 12 V				1	mA
			V_I = –7 V				–0.8	
I_{IH}	High-level enable-input current	V_{IH} = 2.7 V					20	µA
I_{IL}	Low-level enable-input current	V_{IL} = 0.4 V					–100	µA
r_i	Input resistance				12			kΩ
I_{OS}	Short-circuit output current	V_{ID} = 200 mV,	V_O = 0		–15		–85	mA
I_{CC}	Supply current	No load	Receiver outputs enabled, Driver inputs disabled			19	30	mA
			Outputs disabled			19	26	

† All typical values are at V_{CC} = 5 V, T_A = 25°C.
‡ The algebraic convention, in which the less positive (more negative) limit is designated minimum, is used in this data sheet for common-mode input voltage and threshold voltage levels only.
NOTE 6: This applies for both power on and power off. Refer to TIA/EIA-485-A for exact conditions.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature

PARAMETER		TEST CONDITIONS		MIN	TYP†	MAX	UNIT
t_{PLH}	Propagation delay time, low- to high-level output	V_{ID} = –1.5 V to 1.5 V, See Figure 7	C_L = 15 pF,	9	14	19	ns
t_{PHL}	Propagation delay time, high- to low-level output	V_{ID} = –1.5 V to 1.5 V, See Figure 7	C_L = 15 pF,	9	14	19	ns
	Skew ($\|t_{PHL} - t_{PLH}\|$)	V_{ID} = –1.5 V to 1.5 V, See Figure 7	C_L = 15 pF,		2	6	ns
t_{PZH}	Output enable time to high level	C_L = 15 pF,	See Figure 8		7	14	ns
t_{PZL}	Output enable time to low level	C_L = 15 pF,	See Figure 8		7	14	ns
t_{PHZ}	Output disable time from high level	C_L = 15 pF,	See Figure 8		20	35	ns
t_{PLZ}	Output disable time from low level	C_L = 15 pF,	See Figure 8		8	17	ns

† All typical values are at V_{CC} = 5 V, T_A = 25°C.

PARAMETER MEASUREMENT INFORMATION

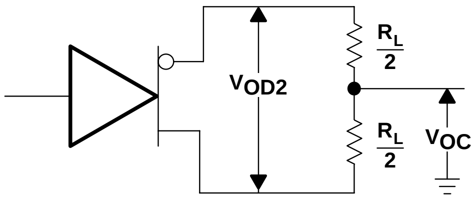


Figure 1. Driver V_{OD} and V_{OC}

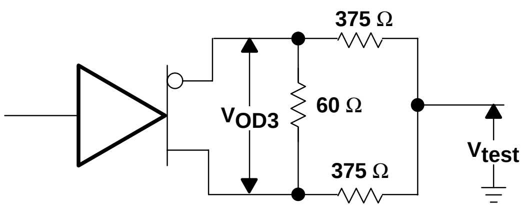
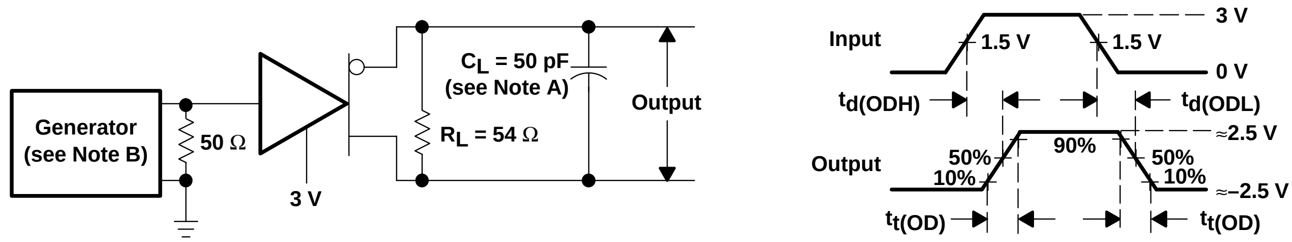


Figure 2. Driver V_{OD3}

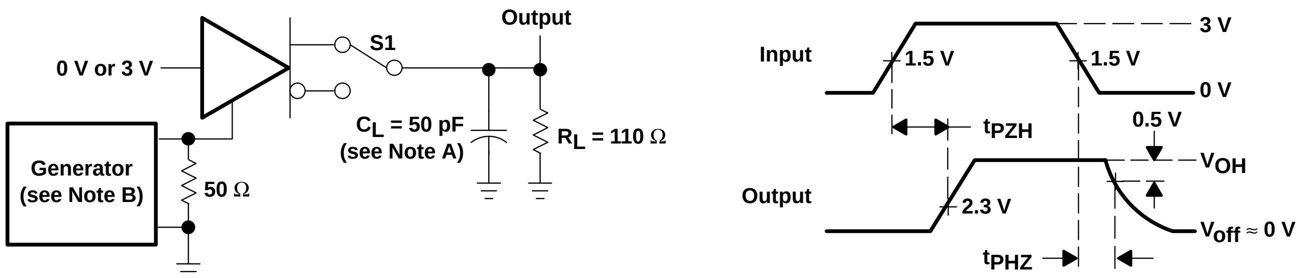
PARAMETER MEASUREMENT INFORMATION



TEST CIRCUIT VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. The input pulse is supplied by a generator having the following characteristics: PRR ≤ 1 MHz, 50% duty cycle, $t_r \le 6$ ns, $t_f \le 6$ ns, $Z_O = 50\ \Omega$.

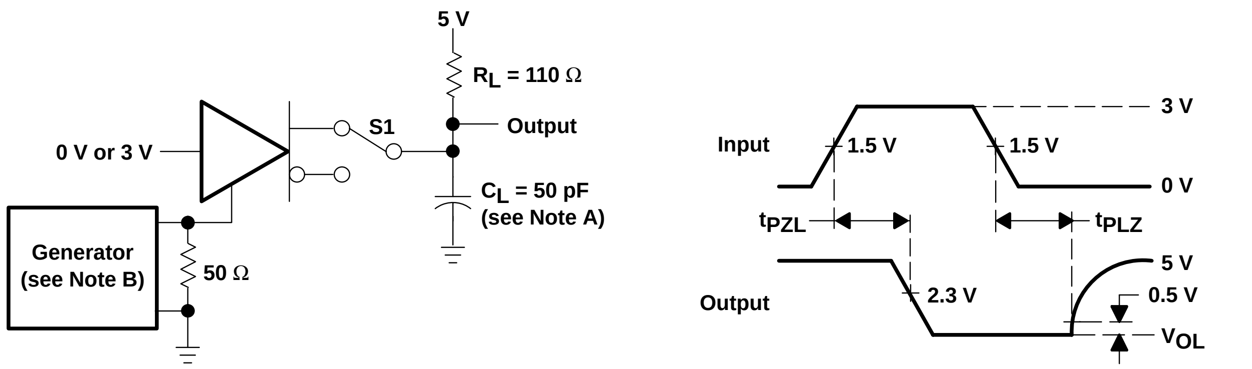
Figure 3. Driver Test Circuit and Voltage Waveforms



TEST CIRCUIT VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. The input pulse is supplied by a generator having the following characteristics: PRR ≤ 1 MHz, 50% duty cycle, $t_r \le 6$ ns, $t_f \le 6$ ns, $Z_O = 50\ \Omega$.

Figure 4. Driver Test Circuit and Voltage Waveforms



TEST CIRCUIT VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. The input pulse is supplied by a generator having the following characteristics: PRR ≤ 1 MHz, 50% duty cycle, $t_r \le 6$ ns, $t_f \le 6$ ns, $Z_O = 50\ \Omega$.

Figure 5. Driver Test Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION

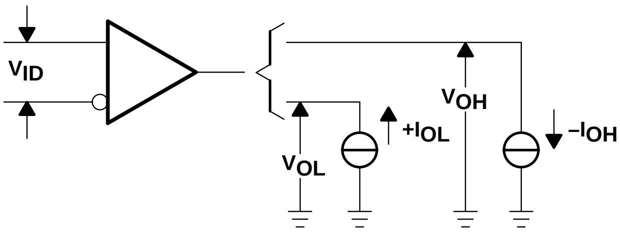
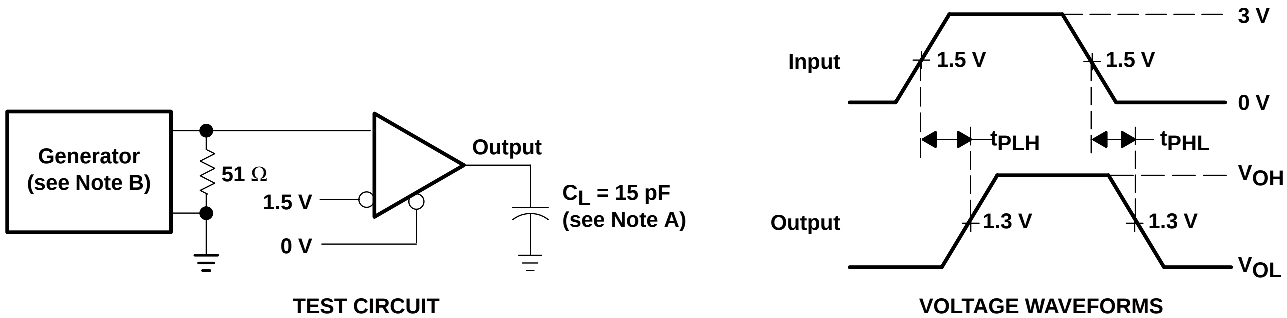


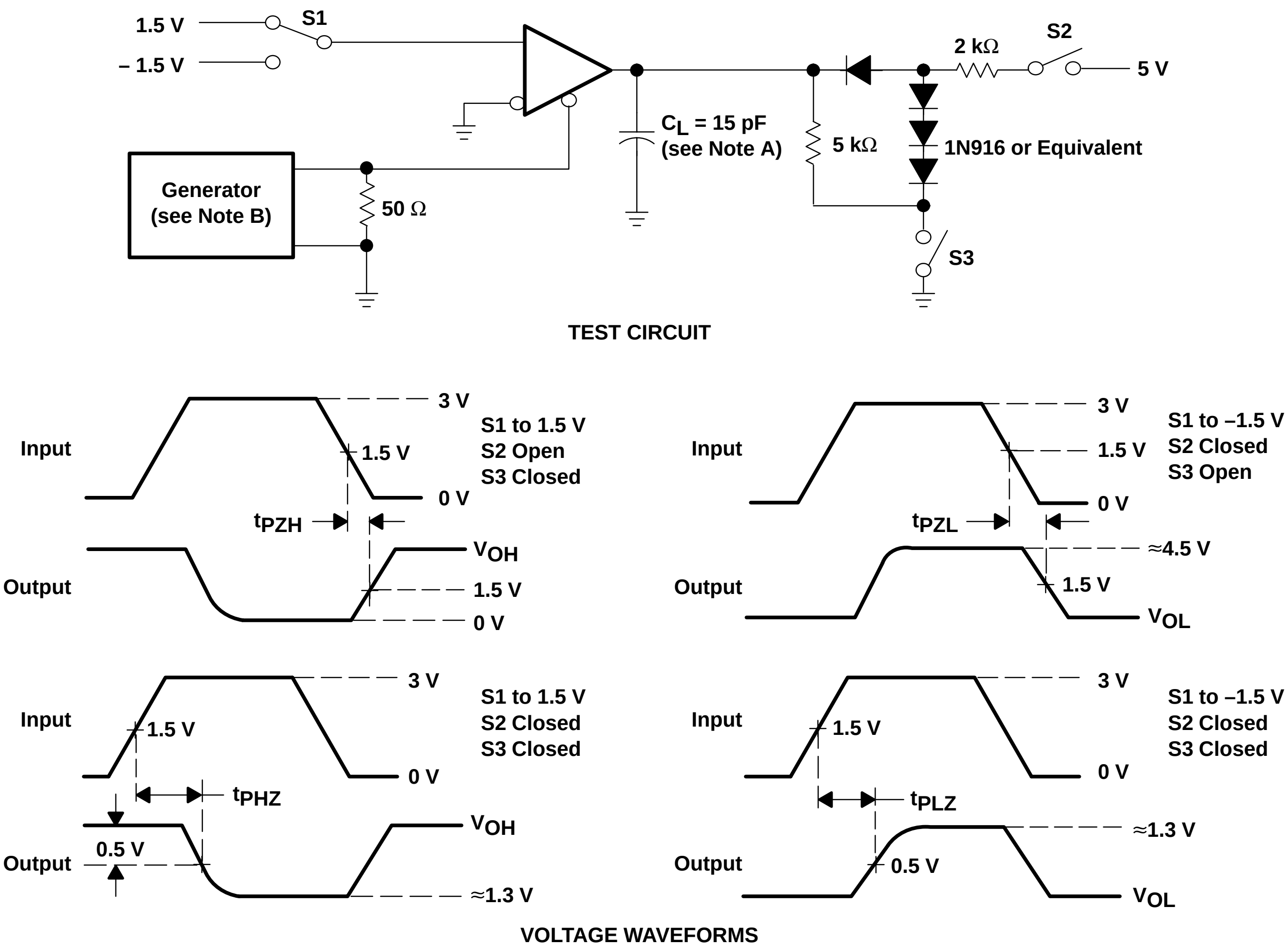
Figure 6. Receiver V_{OH} and V_{OL}



NOTES: A. C_L includes probe and jig capacitance.
B. The input pulse is supplied by a generator having the following characteristics: PRR ≤ 1 MHz, 50% duty cycle, $t_r \leq 6$ ns, $t_f \leq 6$ ns, Z_O = 50 Ω.

Figure 7. Receiver Test Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.
B. The input pulse is supplied by a generator having the following characteristics: PRR ≤ 1 MHz, 50% duty cycle, t_r ≤ 6 ns, t_f ≤ 6 ns, Z_O = 50 Ω.

Figure 8. Receiver Test Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS – DRIVERS

HIGH-LEVEL OUTPUT VOLTAGE
vs
HIGH-LEVEL OUTPUT CURRENT

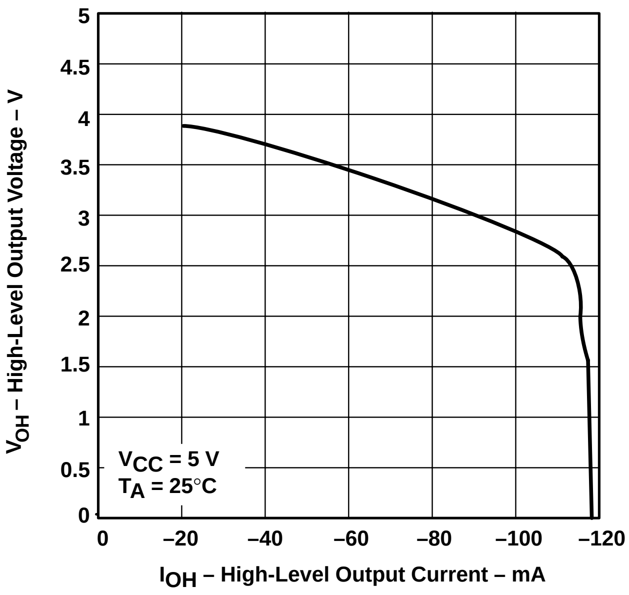


Figure 9

LOW-LEVEL OUTPUT VOLTAGE
vs
LOW-LEVEL OUTPUT CURRENT

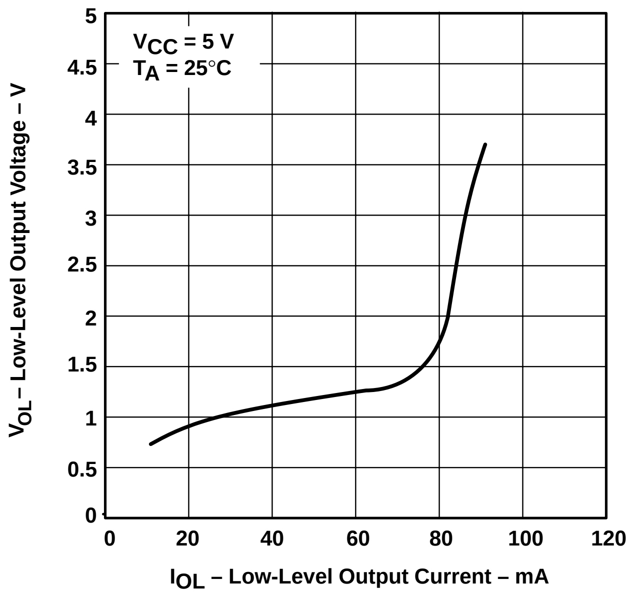


Figure 10

DIFFERENTIAL OUTPUT VOLTAGE
vs
OUTPUT CURRENT

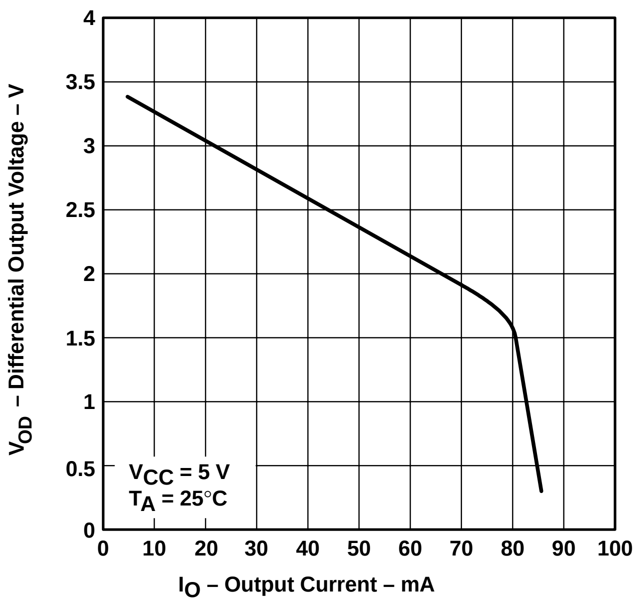


Figure 11

TYPICAL CHARACTERISTICS – RECEIVERS

HIGH-LEVEL OUTPUT VOLTAGE
vs
HIGH-LEVEL OUTPUT CURRENT

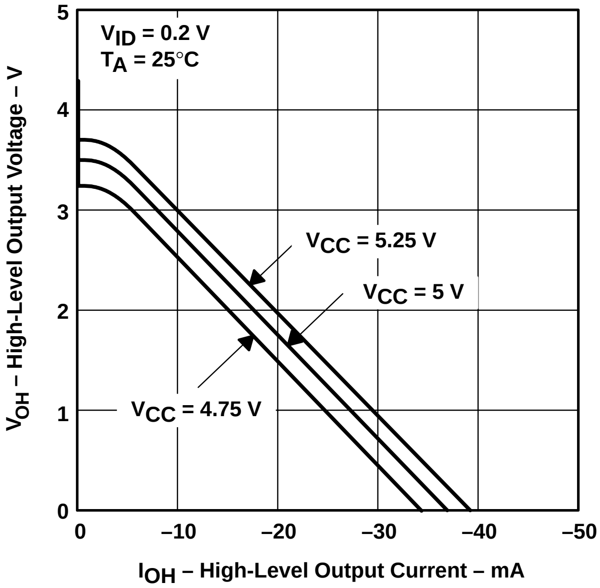


Figure 12

HIGH-LEVEL OUTPUT VOLTAGE
vs
FREE-AIR TEMPERATURE

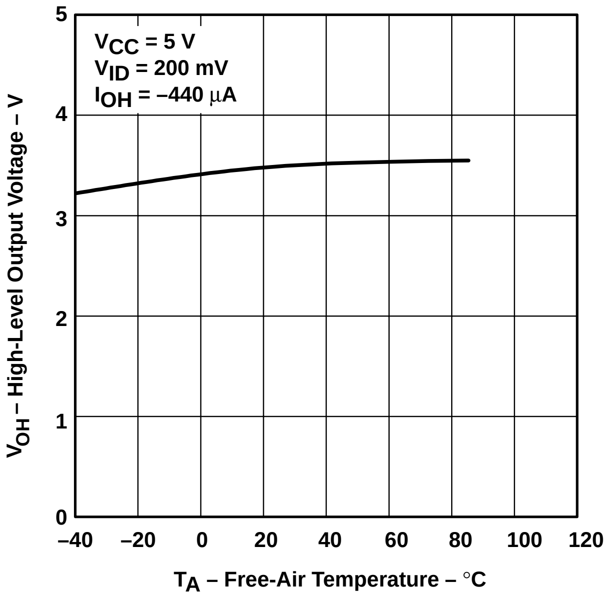


Figure 13

LOW-LEVEL OUTPUT VOLTAGE
vs
LOW-LEVEL OUTPUT CURRENT

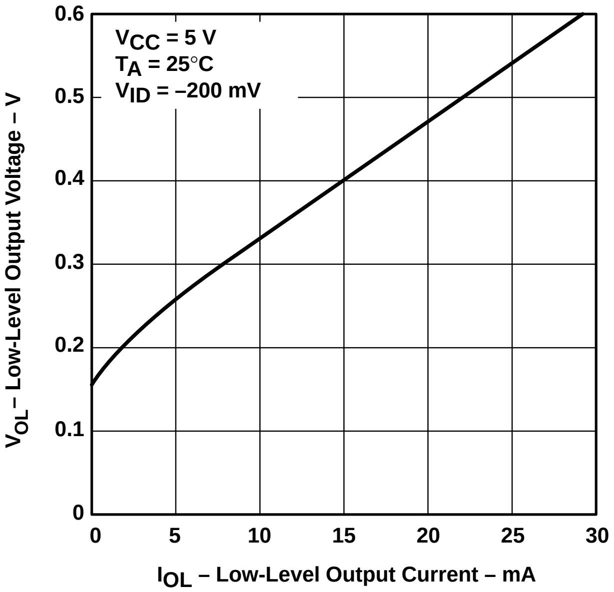


Figure 14

LOW-LEVEL OUTPUT VOLTAGE
vs
FREE-AIR TEMPERATURE

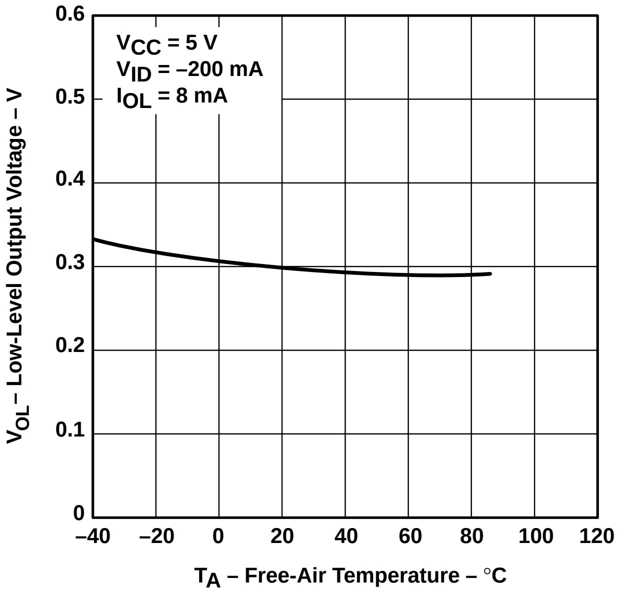


Figure 15

TYPICAL CHARACTERISTICS – RECEIVERS

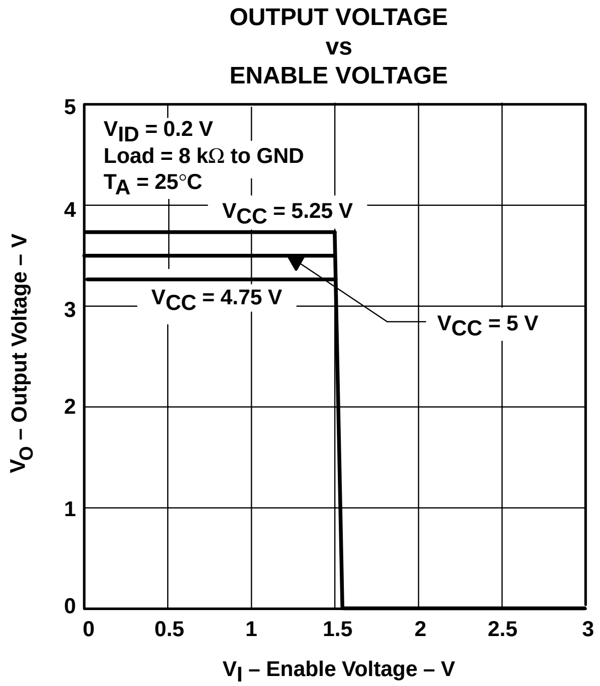


Figure 16

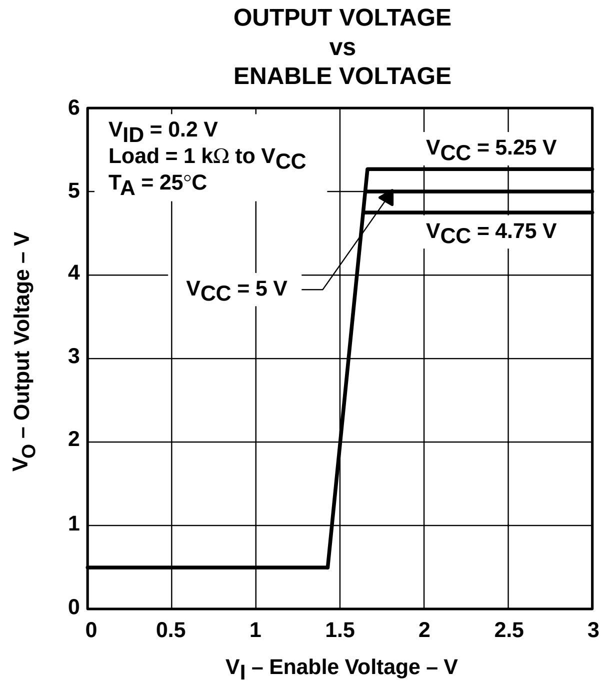
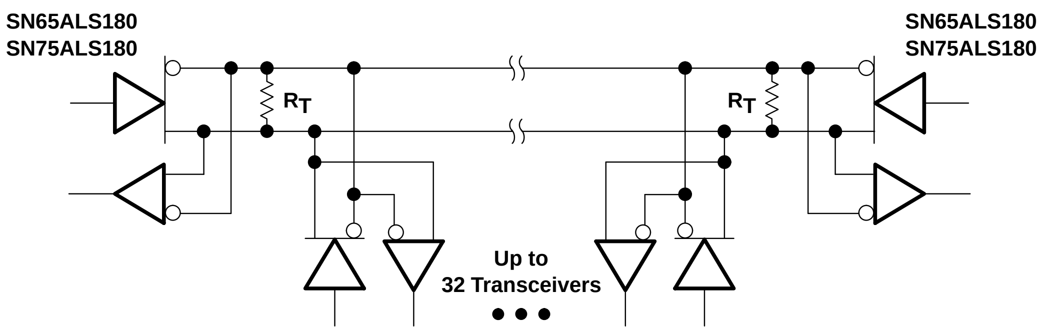


Figure 17

APPLICATION INFORMATION



NOTE A: The line should terminate at both ends in its characteristic impedance ($R_T = Z_O$). Stub lengths off the main line should be kept as short as possible.

Figure 18. Typical Application Circuit

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
SN65ALS180D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65ALS180DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65ALS180DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65ALS180DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65ALS180DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65ALS180DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65ALS180N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN75ALS180D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS180DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS180DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS180DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS180DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS180DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS180N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75ALS180NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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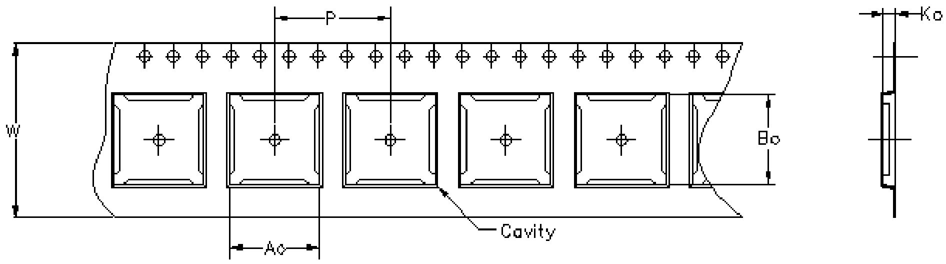
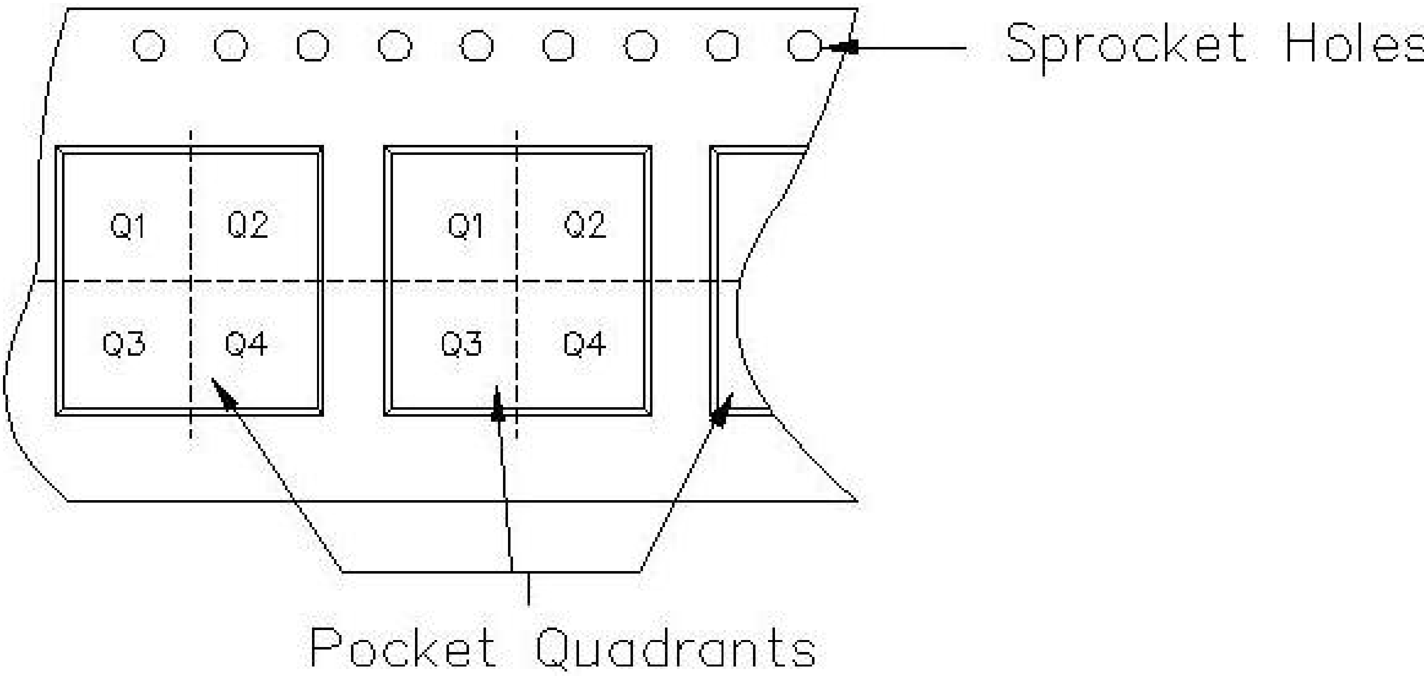


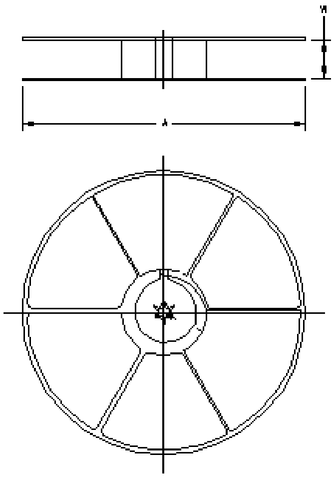
Carrier tape design is defined largely by the component lentgh, width, and thicknes

Ao =	Dimension designed to accommodate the component width.
Bo =	Dimension designed to accommodate the component length.
Ko =	Dimension designed to accommodate the component thickness.
W =	Overall width of the carrier tape.
P =	Pitch between successive cavity centers.



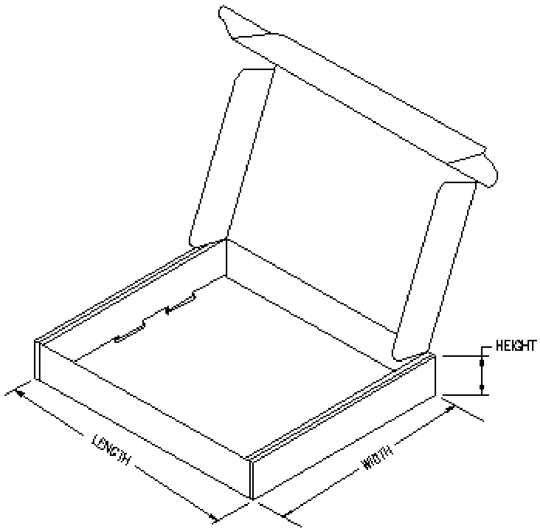
TAPE AND REEL INFORMATION

Device	Package	Pins	Site	Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN65ALS180DR	D	14	MLA	330	16	6.5	9.0	2.1	8	16	Q1
SN75ALS180DR	D	14	MLA	330	16	6.5	9.0	2.1	8	16	Q1



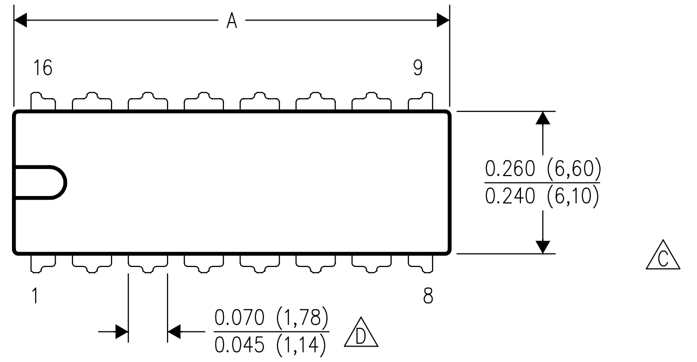
TAPE AND REEL BOX INFORMATION

Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)
SN65ALS180DR	D	14	MLA	342.9	336.6	28.58
SN75ALS180DR	D	14	MLA	342.9	336.6	28.58

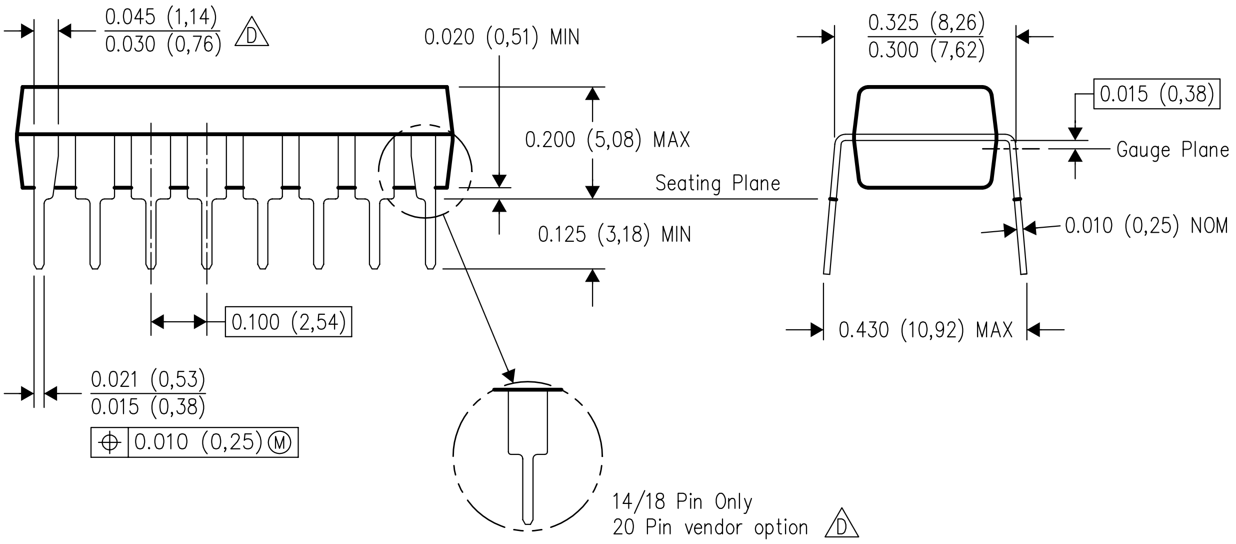


N (R–PDIP–T**) PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



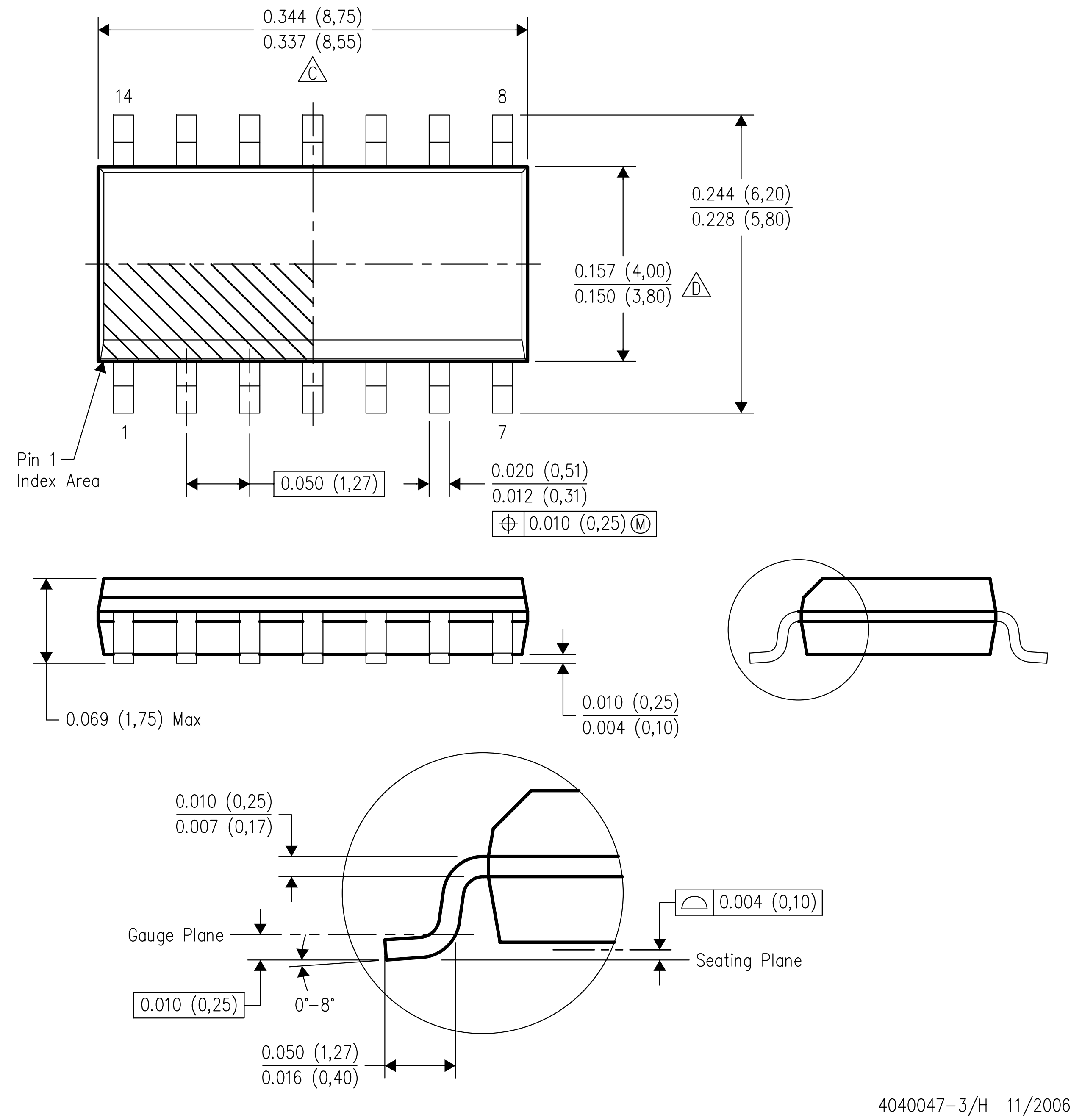
PINS ** / DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G14) PLASTIC SMALL-OUTLINE PACKAGE



NOTES:
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AB.

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